Product Specification

Product:	Conductive Silver Paste
Part Number:	01L-2608B

※ Silver paste cured at 150-200°C
※ Maximum temperature resistance: 300°C, 350°C for 2 hours
※ Suitable for bonding chips, ceramics, glass, and metals
※ Compatible with dispensing and printing processes

Application Scope :
The single-component conductor paste series is a conductive silver paste with reliable adhesion for chip fixation. This paste is suitable for bonding various chips onto substrates such as circuit boards, glass, and ceramics, as well as spotlights. It is designed for flexible circuits requiring temperature resistance above 150°C, demonstrating excellent compatibility with substrates without sagging. Electrodes fabricated with this paste exhibit a glossy, fine-textured appearance and dense structure after curing.

Substrate	Circuit, Glass, Ceramic, Metal, Chip, PI	
Usage Method	Dotting, printing, smearing	
Leveling	Level at room temperature for 3-5 minutes (time adjusted based on actual leveling conditions)	
Solidify	In an incubator, or continuous hot air (choose one of the following conditions)	
	150°C	60 minutes
	180°C	30 minutes
	200°C	30 minutes
	250°C	20 minutes
Viscosity	120-220Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R,10 rpm, with adjustable viscosity at 25±1°C according to user requirements.
Solid Content	65-80%	Silver，Glue
Resistivity	≤20mΩ/□	Square resistance test method (after curing at 300°C for 20 minutes) The cured film thickness is 10μm, and the test pattern size is 100mm*1mm.
	≤10mΩ/□	Four-pin probe method 25.4u

Adhesion	Not fall off	3M 600#Tape 90°Pull
Differences	01L-2608B	Adhesive type, with balanced conductivity, suitable for most products.
	01L-2609S	It exhibits stronger adhesion, though slightly higher resistance than 01L-2608B.

Usage Conditions :

Substrate	Circuit, Glass, Ceramic, Metal, Chip, PI
Usage Method	Dotting, Printing
Leveling	Let it level at room temperature for 5-10 minutes (adjust time based on actual leveling conditions).
Solidify	Furnace drying at 150–200°C for 30 minutes The curing temperature can be within the range of 150-200°C, and the curing time can be determined based on actual conditions.
Thinner	ST-1001

Characteristics :

1. Paste Characteristics :

Characteristic		Standard	Test Method And Conditions
1	Fineness	≤15μm	FOG test
2	Viscosity	80-280Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R,10 rpm, with adjustable viscosity at 25±1°C according to user requirements.
3	Solid Content	70	Silver

2. **Characteristics After Curing :**

Under the condition of 1 sintering, Check fired film produced under the conditions specified in 1）

Characteristics		Standard	Test Method And Conditions
4	Resistivity	≤30mΩ/□	
5	Hardness	4H	Pencil hardness
6	Shear Strength	12Mpa	

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of six months from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.